



# 有铅

Sn63/Pb37 Sn60/Pb40, Sn55Pb45, SnPbBi

\_\_\_\_\_

- 1 0.2mm
- 2 12
- 3
- 4
- 5
- 6 --- PCB
- 7 ICT
- 8 Paste in hole

\_\_\_\_\_

		ROL1	J-STD-004
卤素	0.15wt%		
(SIR)		$1 \times 10^{13}$	25mil
		$1 \times 10^{12}$	40 90%RH 96Hrs
		$1 \times 10^5$	
			IPC-TM-650
			IPC-TM-650
			In house
		85~91wt% ± 0.5	
		9~15wt% ± 0.5	
		220 ± 30 Pa.s Malcolm (10rpm, 2 )	T5, 89% metal for printing
		160 Pa.s ± 10% Malcolm (10rpm, 2 )	T4, 87% metal for syringe
		0.55 ± 0.05	In house
		90%	Copper plate (Sn63, 90% metal)
			J-STD-005
			In house
Vs	48gF	0	IPC-TM-650 ± 5%
	56gF	2	
	68gF	4	
	44gF	8	
		12	In house
			0~10



1

T3 mesh -325/+500 25~45μ m

Fine pitch

2

1) “ ”

0~10

200

4

2)

3

1 ;

3



有铅免洗

0.4mm

0.12mm



有铅免洗

80%

	60 ~ 90HS
	45 <sup>0</sup> ~ 60 <sup>0</sup>
	2 ~ 4 × 10 <sup>5</sup> pa
	20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec
	25 ± 3 40 ~ 70%



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PCB

PCB

A5

200g

B5

300g

A4

400g

4

4

5

6

此有铅



500g

PE

20

35



0 ~10

•

•

0

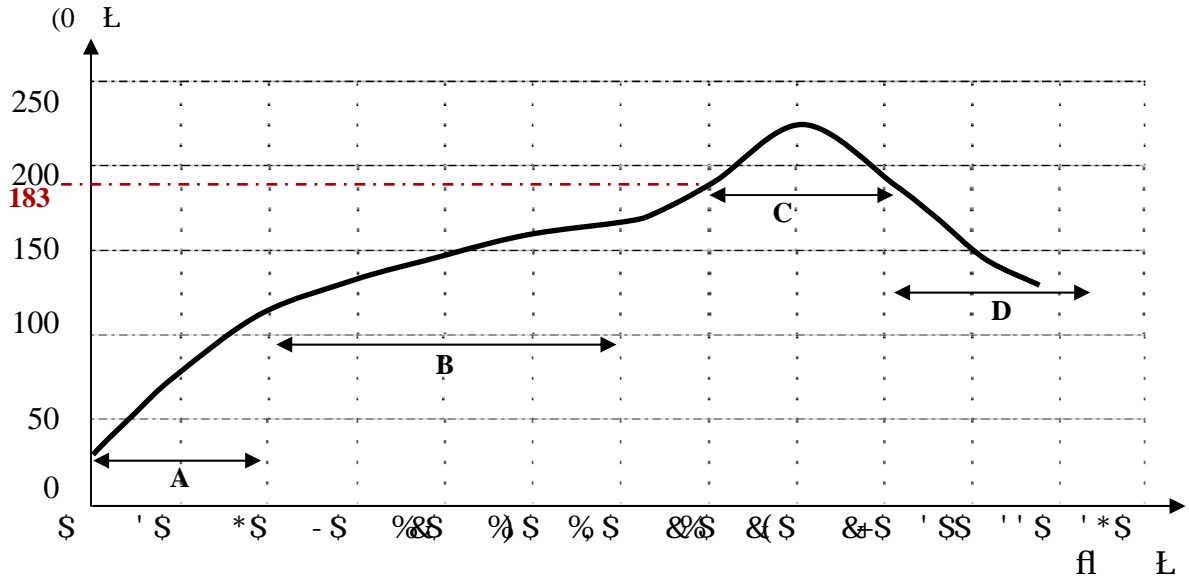
6



MSDS

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A.          25~33%

\* 1.0~3.0 /  
\*

B.                                  33~50%

\* 130~170                                  60~120                                  2 /  
PCB

C.                                 

\* 210~240                                  183                                  40~90                                  Important                                  200                                  20~50  
\*  
\*

D.                                 

\* 4    75  
\*  
\*

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